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Design and Assembly Process Implementation for Ball Grid Arrays (BGAs)

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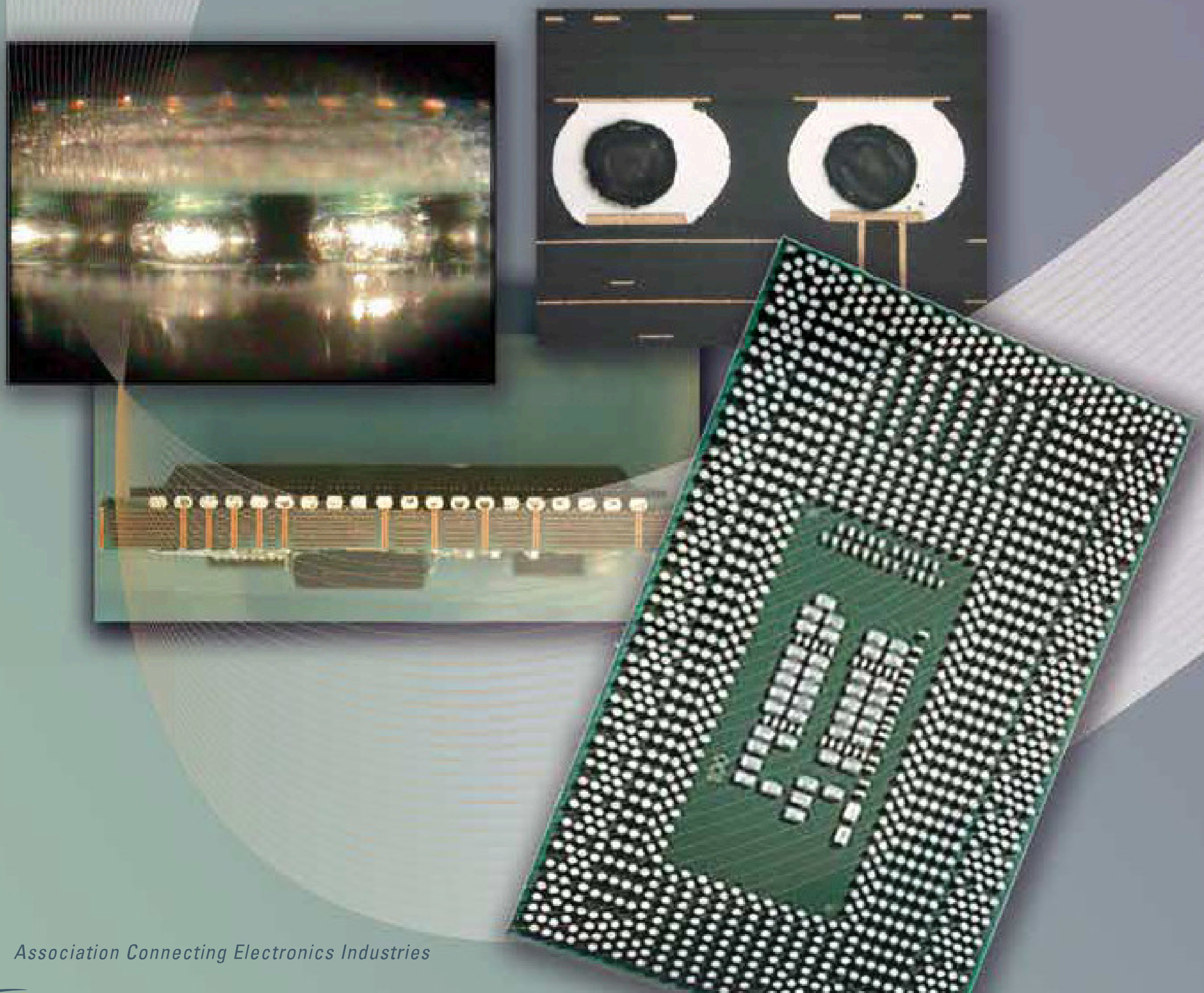

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Developed by the Ball Grid Array Task Group (5-21f) of the
Assembly & Joining Processes Committee (5-20) of IPC

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Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Acknowledgment

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Assembly & Joining Processes Committee

Co-Chairs
Daniel L. Foster
Missile Defense Agency

Leo P. Lambert
EPTAC Corporation

Vice Chair
Karen A. Tellefsen
Alpha Assembly Solutions

Ball Grid Array Task Group

Chair
Ray Prasad
Ray Prasad Consultancy Group

Rob Rowland
Axiom Electronics, LLC

Technical Liaison of the IPC Board of Directors

Bob Neves
Microtek (Changzhou) Laboratories

Ball Grid Array Task Group

Wallace Ables, Dell, Inc.
David Adams, Rockwell Collins
Jamie Albin, Lockheed Martin Space Systems Company
Dudi Amir, Intel Corp.
Richard Arnold, Continental Automotive Systems
Raiyomand Aspandiar, Intel Corp.
Paul Austen, Electronic Controls Design, Inc.
Johnny Baccam, Lockheed Martin Missiles & Fire Control
Elizabeth Benedetto, Hewlett-Packard Company
Gerald Leslie Bogert, Bechtel Plant Machinery, Inc.
Lance Brack, Raytheon Missile Systems
James Daggett, Raytheon Company
Michael Durkan, Mentor Graphics Corporation
Harold Ellison, Quantum Corporation
Gerd Fischer, NASA Goddard Space Flight Center
Joe Fjelstad, Verdant Electronics
Mahendra Gandhi, Northrop Grumman Aerospace Systems
Reza Ghaffarian, Jet Propulsion Laboratory
Ramsey Guy, R & D Assembly
Martin Hart, Topline Corporation
David Hillman, Rockwell Collins
Robert Hills, Tait Electronics
Ife Hsu, Intel Corp.
Greg Hurst, BAE Systems
Jennie Hwang, H-Technologies Group
Richard Iodice, Raytheon Company
Mark Jeanson, IBM Corporation
Sharissa Johns, Lockheed Martin Corporate Engineering
Michael Johnson, M/A-COM Technology Solutions, Inc.
Milea Kammer, Honeywell Aerospace
Joseph Kane, BAE Systems
Matt Kelly, IBM Corporation
Russell Kido, Practical Components Inc.
Vijay Kumar, Lockheed Martin Missile & Fire Control
Kevin Laphen, Practical Components Inc.
David Lober, Kyzen Corporation
Kyle Loomis, Kester
Steve Martell, Sonoscan Inc.
Karen McConnell, Northrop Grumman Corporation
Daniel McCormick, NSWC Crane
Mary Nailos, Dell, Inc.
David Nelson, Adtran Inc.
Jack Olson, Caterpillar Inc.
Mel Parrish, STI Electronics, Inc.
Sam Polk. Lockheed Martin Missiles and Fire Control
Jagadeesh Radhakrishnan, Intel Corp.
Ed Rios, Motorola Solutions
Michael Roth, IBM Corporation
Richard Rumas, Honeywell Aerospace
Francoise Sarrazin, FLEX
Karl Sauter, Oracle America, Inc.
Jeff Schake, ASM Assembly Systems
Martin Scionti, Raytheon Missile Systems
Jeff Shubrooks, Raytheon Company
Vern Solberg, Solberg Technical Consulting
Gregg Stearns, Emerson Climate Technologies- Retail Solutions
John Thompson, FCI USA, Inc.
Kristen Troxel, Hewlett-Packard Company
Penny Valcana, Simulation Technologies
Udo Welzel, Robert Bosch GmbH
Linda Woody, Lockheed Martin Missile & Fire Control
Michael Yuen, Foxconn

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Rob Rowland, Axiom Electronics, LLC

Karen McConnell, Northrop Grumman Corporation

Ife Hsu, Intel Corporation

Bhanu Sood, NASA Goddard Space Flight Center

Dudi Amir, Intel Corporation

John Thompson, FCI USA, Inc.

Raiyomand Aspandiar, Intel Corporation

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